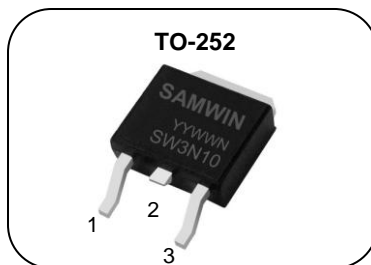


N-channel D-PAK MOSFET

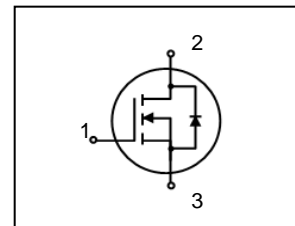
Features

- High ruggedness
- $R_{DS(ON)}$ (Max 107m Ω)@ $V_{GS}=10V$
- Gate Charge (Typical 21nC)
- Improved dv/dt Capability
- 100% Avalanche Tested



1. Gate 2. Drain 3. Source

BV_{DSS} : 100V
 I_D : 3A
 $R_{DS(ON)}$: 107m Ω



General Description

This power MOSFET is produced with advanced VDMOS technology of SAMWIN. This technology enable power MOSFET to have better characteristics, such as fast switching time, low on resistance, low gate charge and especially excellent avalanche characteristics. This power MOSFET is usually used at high efficient DC to DC converter block and switch mode power supply.

Order Codes

Item	Sales Type	Marking	Package	Packaging
1	SW D 3N10	SW3N10	TO-252	REEL

Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DSS}	Drain to Source Voltage	100	V
I_D	Continuous Drain Current (@ $T_C=25^\circ C$)	3*	A
	Continuous Drain Current (@ $T_C=100^\circ C$)	1.9*	A
I_{DM}	Drain current pulsed (note 1)	12	A
V_{GS}	Gate to Source Voltage	± 16	V
E_{AS}	Single pulsed Avalanche Energy (note 2)	187	mJ
E_{AR}	Repetitive Avalanche Energy (note 1)	40	mJ
dv/dt	Peak diode Recovery dv/dt (note 3)	5	V/ns
P_D	Total power dissipation (@ $T_C=25^\circ C$)	44	W
	Derating Factor above 25 $^\circ C$	0.35	W/ $^\circ C$
T_{STG}, T_J	Operating Junction Temperature & Storage Temperature	-55 ~ + 150	$^\circ C$
T_L	Maximum Lead Temperature for soldering purpose, 1/8 from Case for 5 seconds.	300	$^\circ C$

*. Drain current is limited by junction temperature.

Thermal characteristics

Symbol	Parameter	Value	Unit
R_{thic}	Thermal resistance, Junction to case	2.84	$^\circ C/W$
R_{thja}^*	Thermal resistance, Junction to ambient (PCB Mount)		$^\circ C/W$
R_{thia}	Thermal resistance, Junction to ambient	80.2	$^\circ C/W$

*. The value varied due to mounted PCB pad areas

Electrical characteristic ($T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
Off characteristics						
BV_{DSS}	Drain to source breakdown voltage	$V_{GS}=0V, I_D=250\mu A$	100			V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown voltage temperature coefficient	$I_D=250\mu A$, referenced to 25°C		0.11		$V/^\circ\text{C}$
I_{DSS}	Drain to source leakage current	$V_{DS}=100V, V_{GS}=0V$			1	μA
		$V_{DS}=80V, T_C=125^\circ\text{C}$			50	μA
I_{GSS}	Gate to source leakage current, forward	$V_{GS}=16V, V_{DS}=0V$			11	μA
	Gate to source leakage current, reverse	$V_{GS}=-16V, V_{DS}=0V$			11	μA
On characteristics						
$V_{GS(TH)}$	Gate threshold voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.5		2.5	V
$R_{DS(ON)}$	Drain to source on state resistance	$V_{GS}=10V, I_D = 3.5A$		85	107	$m\Omega$
G_{fs}	Forward Transconductance	$V_{DS} = 20 V, I_D = 1.5A$	6			S
Dynamic characteristics						
C_{iss}	Input capacitance	$V_{GS}=0V, V_{DS}=25V, f=1\text{MHz}$		1050		pF
C_{oss}	Output capacitance			65		
C_{rss}	Reverse transfer capacitance			40		
$t_{d(on)}$	Turn on delay time	$V_{DS}=50V, I_D=3A, R_G=25\Omega$ (note 4,5)		8	15	ns
t_r	Rising time			20	35	
$t_{d(off)}$	Turn off delay time			36	50	
t_f	Fall time			18	35	
Q_g	Total gate charge	$V_{DS}=80V, V_{GS}=10V, I_D=3A$ (note 4,5)		21	40	nC
Q_{gs}	Gate-source charge			3		
Q_{gd}	Gate-drain charge			5		

Source to drain diode ratings characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_S	Continuous source current	Integral reverse p-n Junction diode in the MOSFET			3	A
I_{SM}	Pulsed source current				12	A
V_{SD}	Diode forward voltage drop.	$I_S=3A, V_{GS}=0V$			1.5	V
T_{rr}	Reverse recovery time	$I_S=3A, V_{GS}=0V,$		28		ns
Q_{rr}	Breakdown voltage charge	$di_f/dt=100A/\mu s$		38		nC

※. Notes

1. Repeative rating : pulse width limited by junction temperature.
2. $L = 41.6mH, I_{AS} = 3A, V_{DD} = 50V, R_G=25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 3A, di/dt = 100A/\mu s, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$
5. Essentially independent of operating temperature.

Fig. 1. On-state characteristics

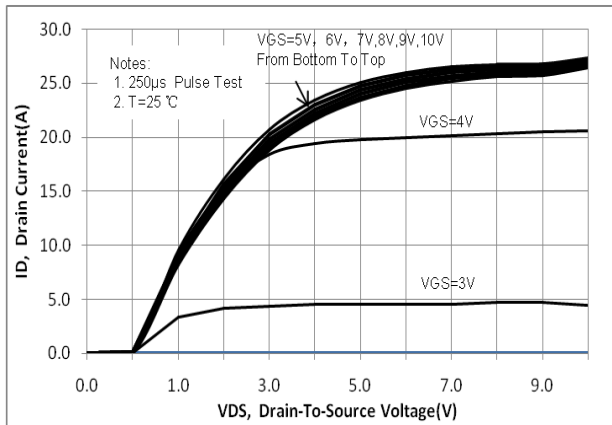


Fig. 2. On-resistance variation vs. drain current and gate voltage

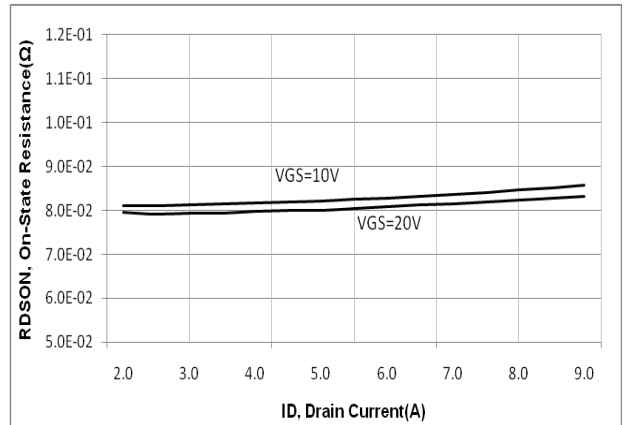


Fig. 3. Gate charge characteristics

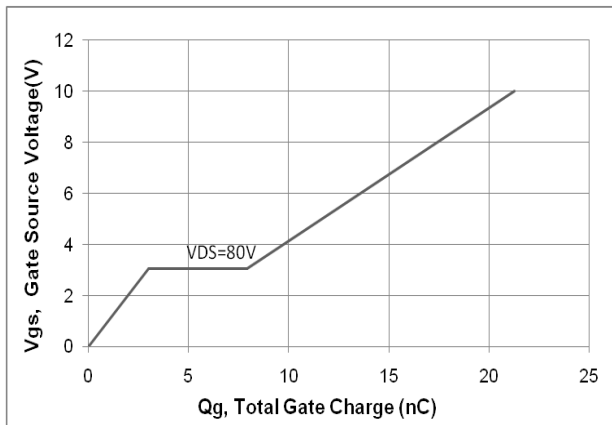


Fig. 4. On state current vs. diode forward voltage

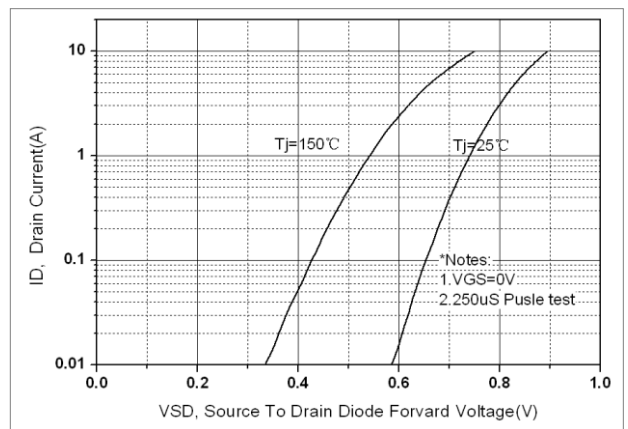


Fig 5. Breakdown Voltage Variation vs. Junction Temperature

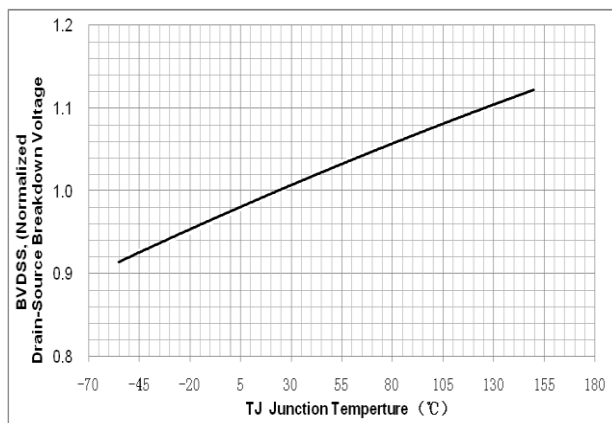


Fig. 6. On resistance variation vs. junction temperature

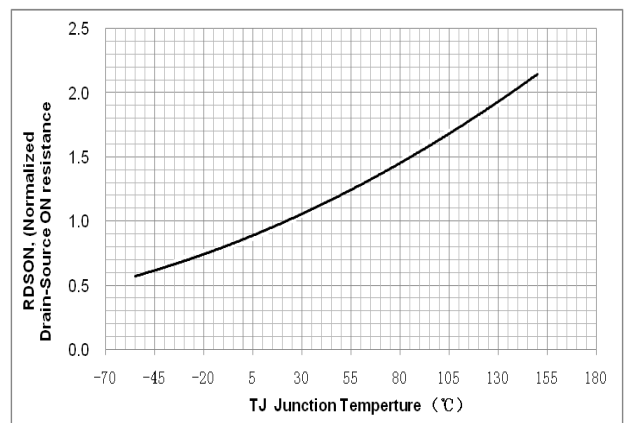


Fig. 7. Maximum safe operating area

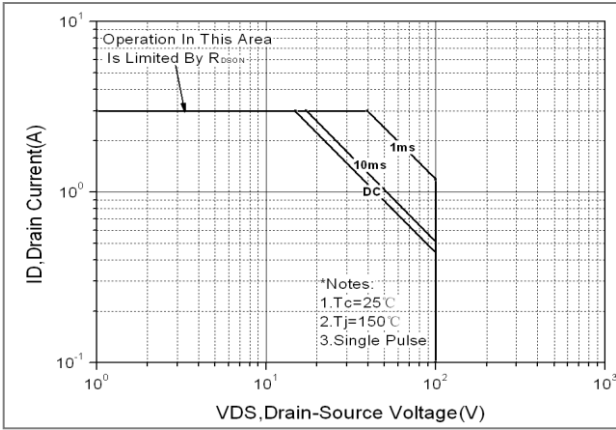


Fig. 8. Transient thermal response curve

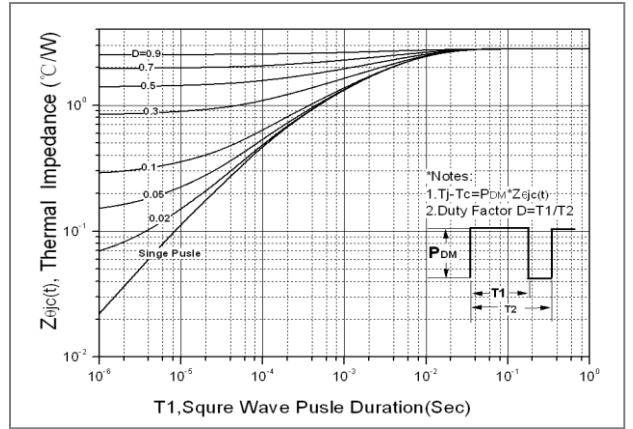


Fig. 9. Gate charge test circuit & waveform

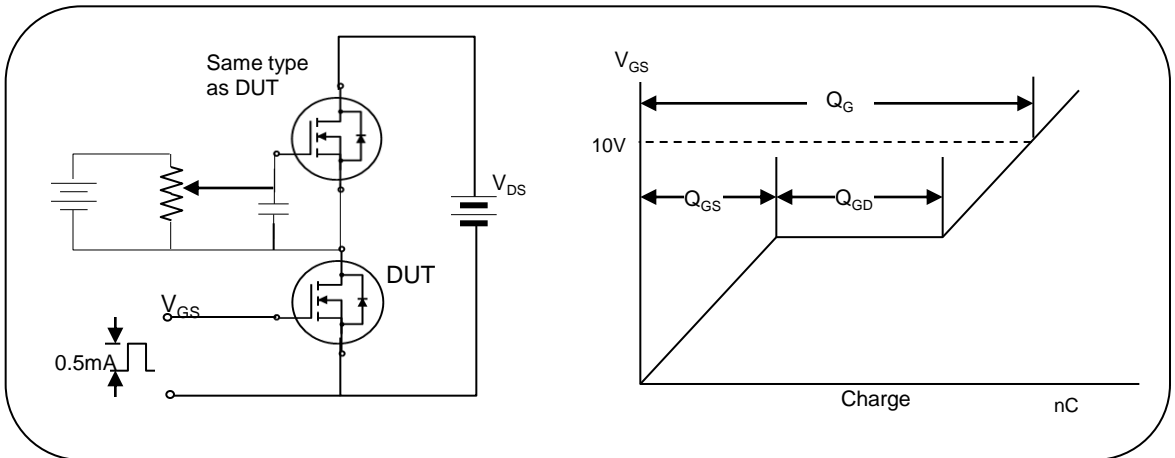


Fig. 10. Switching time test circuit & waveform

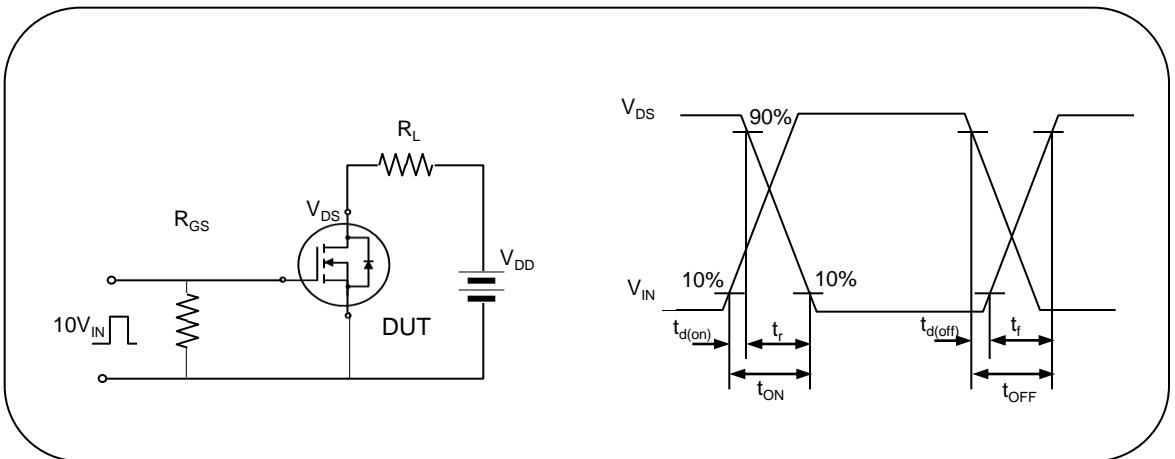


Fig. 11. Unclamped Inductive switching test circuit & waveform

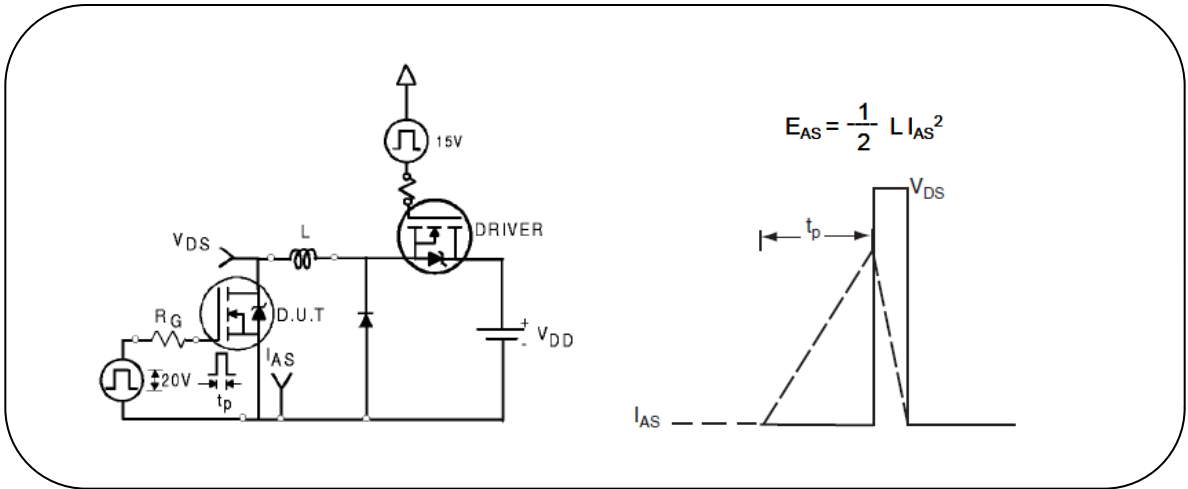


Fig. 12. Peak diode recovery dv/dt test circuit & waveform

